Akashi College				Year 2022			C	Course Title	Micromachine		
Course	Informa	tion			1		1				
Course Code 4041					Course Category Specialize		Specializ	ed / Elective			
Class Format Lecture						· · · · · · · · · · · · · · · · · · ·		•	cademic Credit: 2		
Department Mechanica Engineerir				nd Electronic	Student Grade Adv. 2nd		Adv. 2nd				
Term Second Se				emester		Classes per Week 2		2			
Textbook Teaching											
Instructor MATSUZUKA Naoki											
Course	Objectiv	res									
(2) Under (3) Can e (4) Under (5) Learn	rstand and xplain mic rstand and	l can explai romachines l can explai	n the s fror n det	e principles of m their structu tection princip	materials and car typical semicondu ure to the fabricat iles of sensors and niques. (F) and (F	ictor micromach ion process. (F) d driving principl	ining	techniques			
Rubric						1					
			-	deal Level	Standard Level			Unacceptable Level			
Achievement 1			ch m ca	Fully understand the characteristics of anisotropic material and can accurately calculate the physical property values of crystal orientation.		Understand the characteristics of anisotropic materials and can calculate the physical property values of crystal orientation.		als and car property	Do not understand the characteristics of anisotropic materials and cannot calculate the physical property values of crystal orientation.		
Achievement 2				Fully understar ccurately expl f typical semic nicromachining	Understand and can explain the principles of typical semiconductor micromachining techniques.			Do not understand and cannot explain the principles of typical semiconductor micromachining techniques.			
Achievement 3				Can explain micromachines in detail from their structure to the fabrication process.		Can explain micromachines from their structure to the fabrication process.			Cannot explain micromachines detail from their structure to the fabrication process.		
			ac pi	Fully understand and can accurately explain detection principles of sensors and driving principles of actuators.		Understand and can explain detection principles of sensors and driving principles of actuators.		f sensors	Do not understand and cannot explain detection principles of sensors and driving principles of actuators.		
						Can apply sensor and actuator design techniques.		l actuator	Cannot apply sensor and actuator design techniques.		
Assigne	d Depar	tment Ol	ojec	tives							
Teachin	g Metho	d									
Outline sensors, a in a wide techniques				hines or micro electro mechanical systems (MEMS) are devices that integrate micro structures, actuators, and electronic circuits using semiconductor micromachining technology. They are applied range of fields. The first half of this course will explain typical semiconductor micromachining es and micromachine fabrication methods. The second half will explain the principles of sensors used nachines, driving principles of actuators, typical sensors, and actuator design techniques.							
Style											
Notice	This course's content will amount to 90 hours of study in total. These hours include the learning time guaranteed in classes and the standard self-study time required for pre-study / review, and completing assignment reports. It is recommended that students have a basic knowledge of engineering materials										
Charact	eristics			vision in Lea				<u>-</u>			
□ Active Learning				Aided by IC	Applicable to Remote Class			Instructor Professionally Experienced			
Course	Plan	· · · · · ·									
			Ther	me			Goals				
2nd Semeste r	3rd Quarter	1st	An c	overview of m	and scaling laws		caling laws				
		2nd	Phys	sical propertie	silicon (1) methods and and crystal silicon.		ods and ar al silicon.	crystal structure, manufacturing sotropic properties of single-			
		3rd	Phys	sical propertie			cal propert	calculation method for the es in arbitrary crystal orientation silicon.			
		4th	Photolithography						principles of photolithography.		
		5th	Film	deposition (1	Understand the s chemical vapor d		rstand the ical vapor	sputter, vapor deposition, and leposition methods.			
		6th	Film	deposition (2			stand the	rmal oxidation and impurity			
		7th	Etching (1)				Under etchin	Jnderstand liquid-based isotropic and anisot atching of single-crystal silicon.			
		8th	Etching (2)					-based dry-etching.			
	4th Quarter	9th	Micr	omachine fab	rication technolog	y	Understand micromachine fabrication processes using semiconductor micromachining techniques.				

		10th	Sensor design teo	chnology (1)		Understand typical micro-sensors and sensing principles.				
	11th		Sensor design teo	chnology (2)		Understand he sensors.	Understand how to design piezoresistive pressure sensors.			
		12th	Sensor design teo	chnology (3)		Design a piezo	Design a piezoresistive pressure sensor.			
		13th Actuator design technology (1)				Understand typical micro actuators and their driving principles.				
		14th	Actuator design to	echnology (2)		Understand he actuator.	Understand how to design an electrostatic drive actuator.			
	15th		Actuator design to	echnology (3)		Design a elect	Design a electrostatic drive actuator.			
		16th Final exam								
Evaluati	on Me	ethod and	Weight (%)							
		Examination	Assignments	Mutual Evaluations between students	Behavior	Portfolio	Other	Total		
Subtotal		60	40	0	0	0	0	100		
Basic Proficiency		0	0 0		0	0	0	0		
Specialized Proficiency		60	40	0	0	0	0	100		
Cross Area Proficiency		0	0	0	0	0	0	0		